

# BLF3G21-30

UHF power LDMOS transistor

Rev. 01 — 14 February 2007

Product data sheet

## 1. Product profile

### 1.1 General description

30 W LDMOS power transistor for base station applications at frequencies from HF to 2200 MHz.

**Table 1. Typical class-AB RF performance**

$I_{Dq} = 450 \text{ mA}$ ;  $T_h = 25^\circ\text{C}$  in a common source test circuit.

Mode of operation	f (MHz)	$P_L$ (W)	$G_p$ (dB)	$\eta_D$ (%)	IMD3 (dB)	$P_{L(1dB)}$ (W)
CW	2000	36	12.5	43	-	36
Two-tone	2000	30	13.5	35	-26	-
		0.1 to 10	13.8	-	< -50	-

**Table 2. Typical class-A RF performance**

$I_{Dq} = 1 \text{ A}$ ;  $T_h = 25^\circ\text{C}$  in a modified PHS test fixture.

Mode of operation	f (MHz)	$P_{L(AV)}$ (W)	$G_p$ (dB)	$\eta_D$ (%)	ACPR <sub>600</sub> (dBc)
PHS	1880 to 1920	9	16	20	-75

#### CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Therefore care should be taken during transport and handling.

### 1.2 Features

- Excellent back-off linearity
- Typical PHS performance at a supply voltage of 26 V and  $I_{Dq}$  of 1 A:
  - ◆ Average output power = 9 W
  - ◆ Gain = 16 dB (typ)
  - ◆ Efficiency = 20 %
  - ◆ ACPR<sub>600</sub> = -75 dBc
- Easy power control
- Excellent ruggedness
- High power gain
- Excellent thermal stability
- Designed for broadband operation (HF to 2200 MHz)

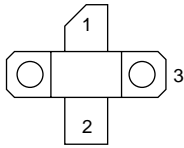
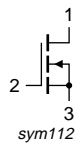
- No internal matching for broadband operation
- ESD protection

### 1.3 Applications

- RF power amplifiers for GSM, PHS, EDGE, CDMA and W-CDMA base stations and multicarrier applications in the HF to 2200 MHz frequency range
- Broadcast drivers

## 2. Pinning information

**Table 3. Pinning**

Pin	Description	Simplified outline	Symbol
1	drain		
2	gate		
3	source		

[1] Connected to flange

## 3. Ordering information

**Table 4. Ordering information**

Type number	Package		
	Name	Description	Version
BLF3G21-30	-	flanged LDMOST ceramic package; 2 mounting holes; 2 leads	SOT467C

## 4. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	drain-source voltage		-	65	V
$V_{GS}$	gate-source voltage		-	±15	V
$I_D$	drain current		-	4.5	A
$T_{stg}$	storage temperature		-65	+150	°C
$T_j$	junction temperature		-	200	°C

## 5. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-c)}$	thermal resistance from junction to case	$T_h = 25\text{ °C}; P_{L(AV)} = 15\text{ W}$	[1] 1.6	K/W
$R_{th(j-h)}$	thermal resistance from junction to heatsink	$T_h = 25\text{ °C}; P_{L(AV)} = 15\text{ W}$	[2] 2.1	K/W

[1] Thermal resistance is determined under specified RF operating conditions

[2] Depending on mounting condition in application

## 6. Characteristics

**Table 7. Characteristics**

$T_j = 25\text{ °C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{(BR)DSS}$	drain-source breakdown voltage	$V_{GS} = 0\text{ V}; I_D = 0.7\text{ mA}$	65	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$V_{DS} = 10\text{ V}; I_D = 70\text{ mA}$	2.0	-	3.0	V
$I_{DSS}$	drain leakage current	$V_{GS} = 0\text{ V}; V_{DS} = 28\text{ V}$	-	-	5	$\mu\text{A}$
$I_{DSX}$	drain cut-off current	$V_{GS} = V_{GS(th)} + 9\text{ V}; V_{DS} = 10\text{ V}$	9	-	-	A
$I_{GSS}$	gate leakage current	$V_{GS} = \pm 15\text{ V}; V_{DS} = 0\text{ V}$	-	-	11	nA
$g_{fs}$	transfer conductance	$V_{DS} = 10\text{ V}; I_D = 2.5\text{ A}$	-	3	-	S
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 9\text{ V}; I_D = 2.5\text{ A}$	-	0.3	-	$\Omega$
$C_{rs}$	feedback capacitance	$V_{GS} = 0\text{ V}; V_{DS} = 28\text{ V}; f = 1\text{ MHz}$	-	1.7	-	pF

## 7. Application information

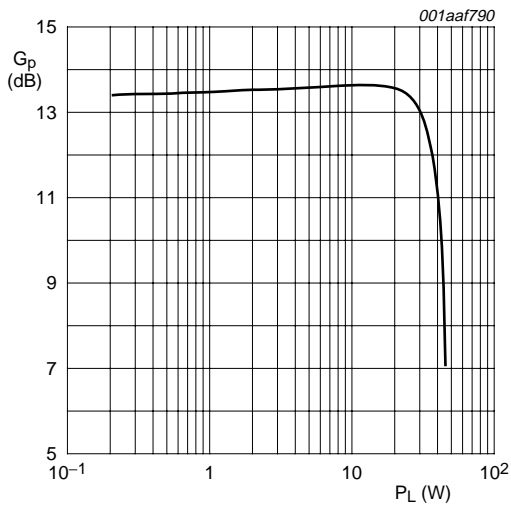
**Table 8. Application information**

$V_{DS} = 26\text{ V}; T_h = 25\text{ °C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Mode of operation: Two-tone CW (100 kHz tone spacing); <math>f = 2000\text{ MHz}; I_{Dq} = 450\text{ mA}</math></b>						
$G_p$	power gain	$P_{L(PEP)} = 30\text{ W}$	12.5	13.5	-	dB
$RL_{in}$	input return loss	$P_{L(PEP)} = 30\text{ W}$	-	-16	-11	dB
$\eta_D$	drain efficiency	$P_{L(PEP)} = 30\text{ W}$	32	35.0	-	%
IMD3	third order intermodulation distortion	$P_{L(PEP)} = 30\text{ W}$	-	-26	-23	dBc
		$P_{L(PEP)} < 10\text{ W}$	-	< -50	-	dBc
<b>Mode of operation: one-tone CW; <math>f = 2000\text{ MHz}; I_{Dq} = 450\text{ mA}</math></b>						
$G_p$	power gain	$P_L = P_{L(1dB)} = 36\text{ W}$	-	12.5	-	dB
$\eta_D$	drain efficiency	$P_L = P_{L(1dB)} = 36\text{ W}$	-	43	-	%
<b>Mode of operation: PHS; <math>f = 1900\text{ MHz}; I_{Dq} = 1\text{ A}</math></b>						
$G_p$	power gain	$P_{L(AV)} = 9\text{ W}$	-	16	-	dB
$\eta_D$	drain efficiency	$P_{L(AV)} = 9\text{ W}$	-	20	-	%

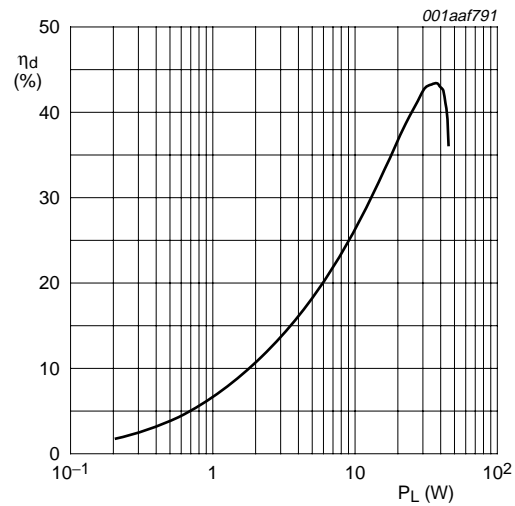
**7.1 Ruggedness in class-AB operation**

The BLF3G21-30 is capable of withstanding a load mismatch corresponding to VSWR = 10 : 1 through all phases under the following conditions:  $V_{DS} = 26\text{ V}$ ;  $f = 2200\text{ MHz}$  at rated load power.



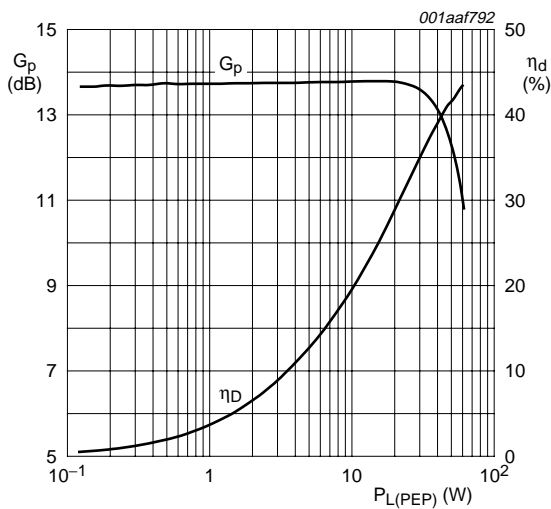
$V_{DS} = 26\text{ V}$ ;  $I_{Dq} = 450\text{ mA}$ ;  $T_h = 25\text{ }^\circ\text{C}$ ;  $f = 2000\text{ MHz}$

**Fig. 1. Power gain as function of CW load power; typical values**



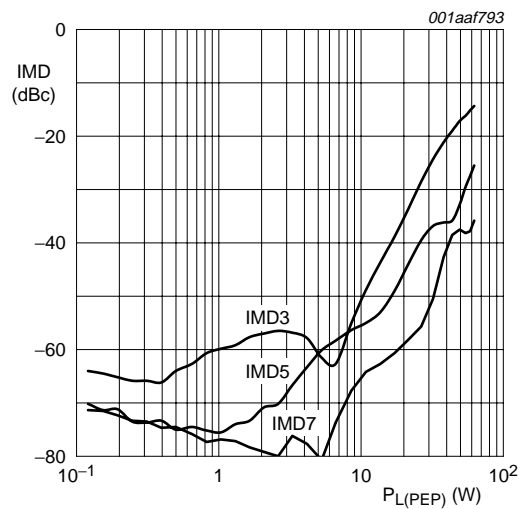
$V_{DS} = 26\text{ V}$ ;  $I_{Dq} = 450\text{ mA}$ ;  $T_h = 25\text{ }^\circ\text{C}$ ;  $f = 2000\text{ MHz}$

**Fig. 2. Drain efficiency as function of CW load power; typical values**



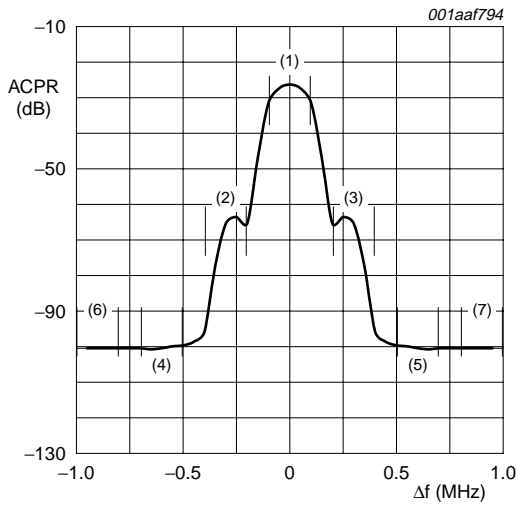
$V_{DS} = 26\text{ V}$ ;  $I_{Dq} = 450\text{ mA}$ ;  $T_h \leq 25\text{ }^\circ\text{C}$ ;  
 $f_1 = 2000\text{ MHz}$ ;  $f_2 = 2000.1\text{ MHz}$

**Fig. 3. Two-tone power gain and drain efficiency as functions of peak envelope load power; typical values**



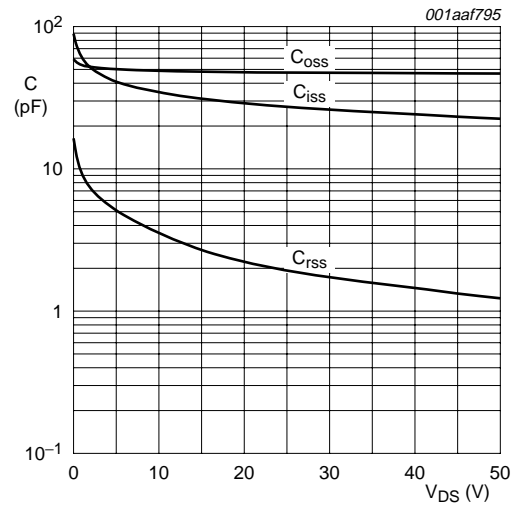
$V_{DS} = 26\text{ V}$ ;  $I_{Dq} = 450\text{ mA}$ ;  $T_h \leq 25\text{ }^\circ\text{C}$ ;  
 $f_1 = 2000\text{ MHz}$ ;  $f_2 = 2000.1\text{ MHz}$

**Fig. 4. Two-tone intermodulation distortion as function of peak envelope load power; typical values**

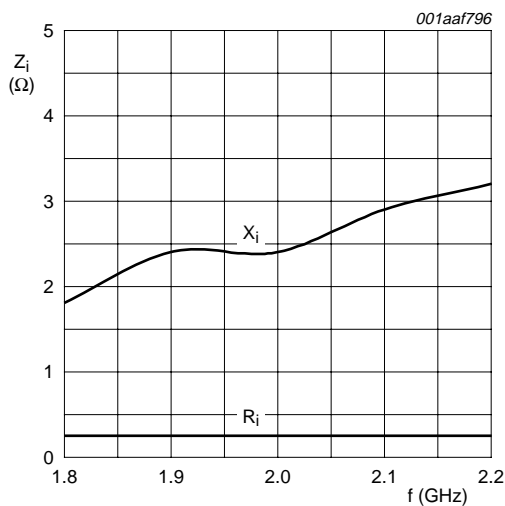


(1) 192 kHz channel bandwidth  
 (2)  $-ACPR_{300}$  at 192 kHz bandwidth  
 (3)  $+ACPR_{300}$  at 192 kHz bandwidth  
 (4)  $-ACPR_{600}$  at 192 kHz bandwidth  
 (5)  $+ACPR_{600}$  at 192 kHz bandwidth  
 (6)  $-ACPR_{900}$  at 192 kHz bandwidth  
 (7)  $+ACPR_{900}$  at 192 kHz bandwidth  
 $V_{DS} = 26\text{ V}$ ;  $I_{DQ} = 1000\text{ mA}$ ;  $T_h \leq 25\text{ }^\circ\text{C}$ ;  
 $f_c = 1900\text{ MHz}$ ;  $P_{L(AV)} = 9\text{ W}$

**Fig 5. ACPR performance under PHS conditions, measured in application board**

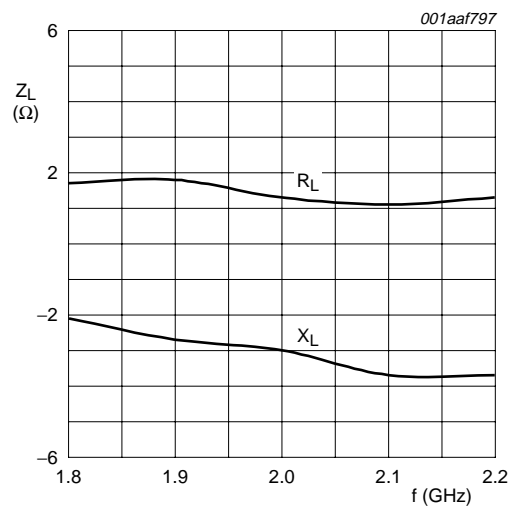


**Fig 6.  $C_{iss}$ ,  $C_{rss}$  and  $C_{oss}$  as functions of drain supply voltage; typical values**



$V_{DS} = 26\text{ V}$ ;  $I_{DQ} = 450\text{ mA}$ ;  $P_L = 45\text{ W}$ ;  $T_h \leq 25\text{ }^\circ\text{C}$

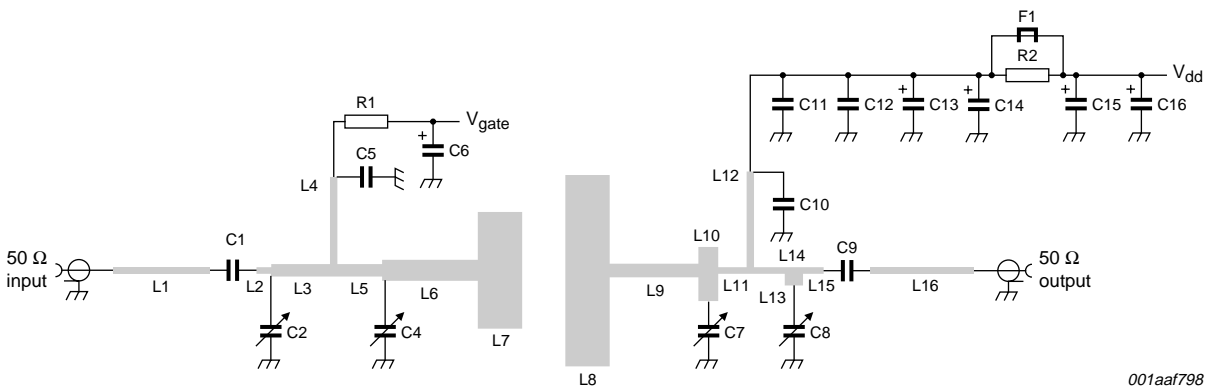
**Fig 7. Input impedance as function of frequency (series components); typical values**



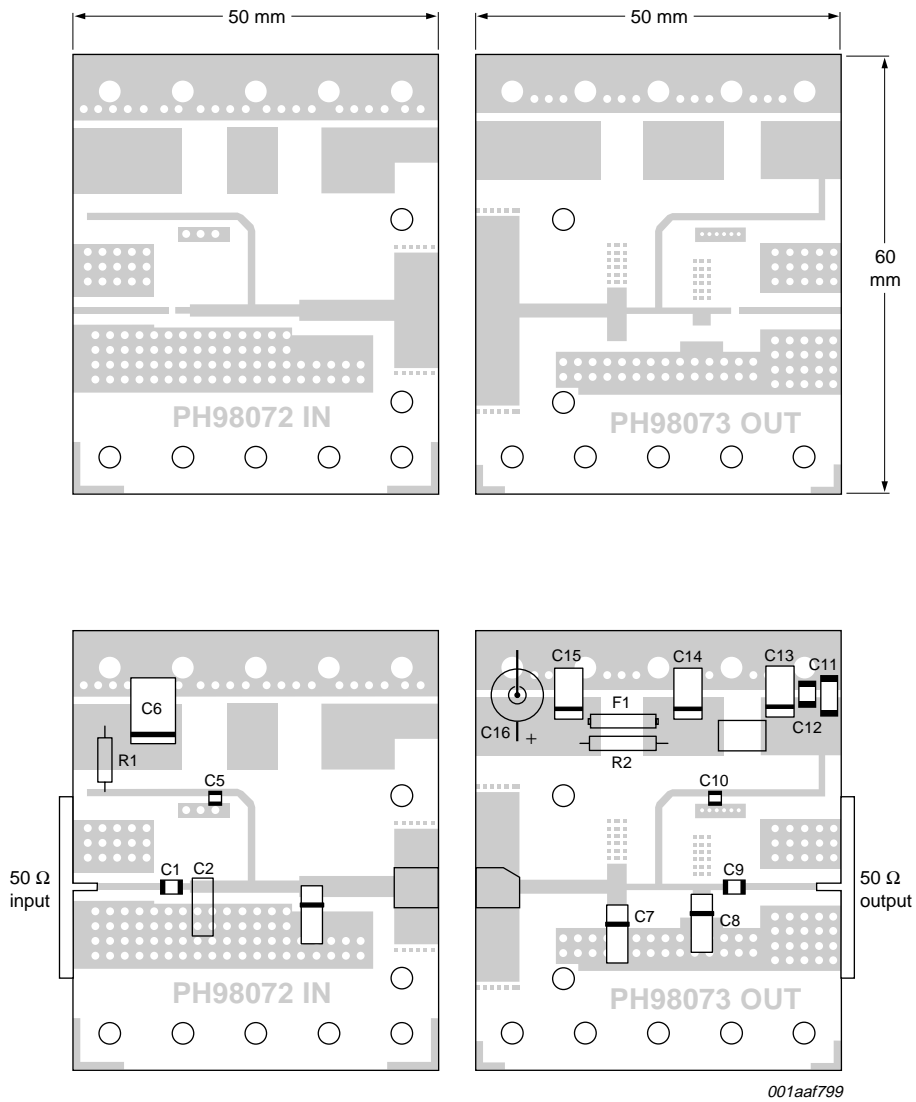
$V_{DS} = 26\text{ V}$ ;  $I_{DQ} = 450\text{ mA}$ ;  $P_L = 45\text{ W}$ ;  $T_h \leq 25\text{ }^\circ\text{C}$

**Fig 8. Load impedance as function of frequency (series components); typical values**

**8. Test information**



**Fig 9. Class-AB test circuit for 2 GHz**



The components are situated on one side of the copper-clad Printed-Circuit Board (PCB) with Teflon dielectric ( $\epsilon_r = 6.15$ ); thickness = 0.64 mm. The other side is unetched and serves as a ground plane.

See [Table 9](#) for a list of components.

**Fig 10. Component layout for 2 GHz class-AB test circuit**

Table 9. List of components (see Figure 9 and Figure 10)

Component	Description	Value	Dimensions	Catalogue No.
C1, C9	multilayer ceramic chip capacitor	[2] 11 pF		
C2, C4, C7, C8	Tekelec variable capacitor; type 37271	0.6 pF to 4.5 pF		
C5, C10	multilayer ceramic chip capacitor	[1] 12 pF		
C6, C13, C14, C15	tantalum SMD capacitor	4.5 $\mu$ F; 50 V		
C11	multilayer ceramic chip capacitor	[2] 1 nF		
C12	multilayer ceramic chip capacitor	100 nF		2222 581 16641
C16	electrolytic capacitor	100 $\mu$ F; 63 V		2222 037 58101
F1	ferrite SMD bead		8DS3/3/8/9-4S2	4330 030 36301
L1	stripline	[3] 50 $\Omega$	13 mm $\times$ 0.9 mm	
L2	stripline	[3] 50 $\Omega$	2 mm $\times$ 0.9 mm	
L3	stripline	[3] 34.3 $\Omega$	15 mm $\times$ 1.7 mm	
L4, L12	stripline	[3] 50 $\Omega$	37 mm $\times$ 0.9 mm	
L5	stripline	[3] 34.3 $\Omega$	6 mm $\times$ 1.7 mm	
L6	stripline	[3] 23.6 $\Omega$	13 mm $\times$ 2.9 mm	
L7	stripline	[3] 5.6 $\Omega$	6 mm $\times$ 15.8 mm	
L8	stripline	[3] 3.5 $\Omega$	6 mm $\times$ 26 mm	
L9	stripline	[3] 31.9 $\Omega$	12 mm $\times$ 1.9 mm	
L10	stripline	[3] 24.9 $\Omega$	7.4 mm $\times$ 2.7 mm	
L11	stripline	[3] 50 $\Omega$	3 mm $\times$ 0.9 mm	
L13	stripline	[3] 50 $\Omega$	4.15 mm $\times$ 0.9 mm	
L14	stripline	[3] 26.3 $\Omega$	2.5 mm $\times$ 2.5 mm	
L15	stripline	[3] 50 $\Omega$	2.8 mm $\times$ 0.9 mm	
L16	stripline	[3] 50 $\Omega$	14 mm $\times$ 0.9 mm	
R1, R2	metal film resistor	10 $\Omega$ ; 0.6 W		2322 156 11009

[1] American Technical Ceramics type 100B or capacitor of same quality

[2] American Technical Ceramics type 100A or capacitor of same quality

[3] The striplines are on a double copper-clad Printed-Circuit Board (PCB) with Teflon dielectric ( $\epsilon_r = 6.15$ ); thickness = 0.64 mm



9. Package outline

Flanged LDMOST ceramic package; 2 mounting holes; 2 leads

SOT467C

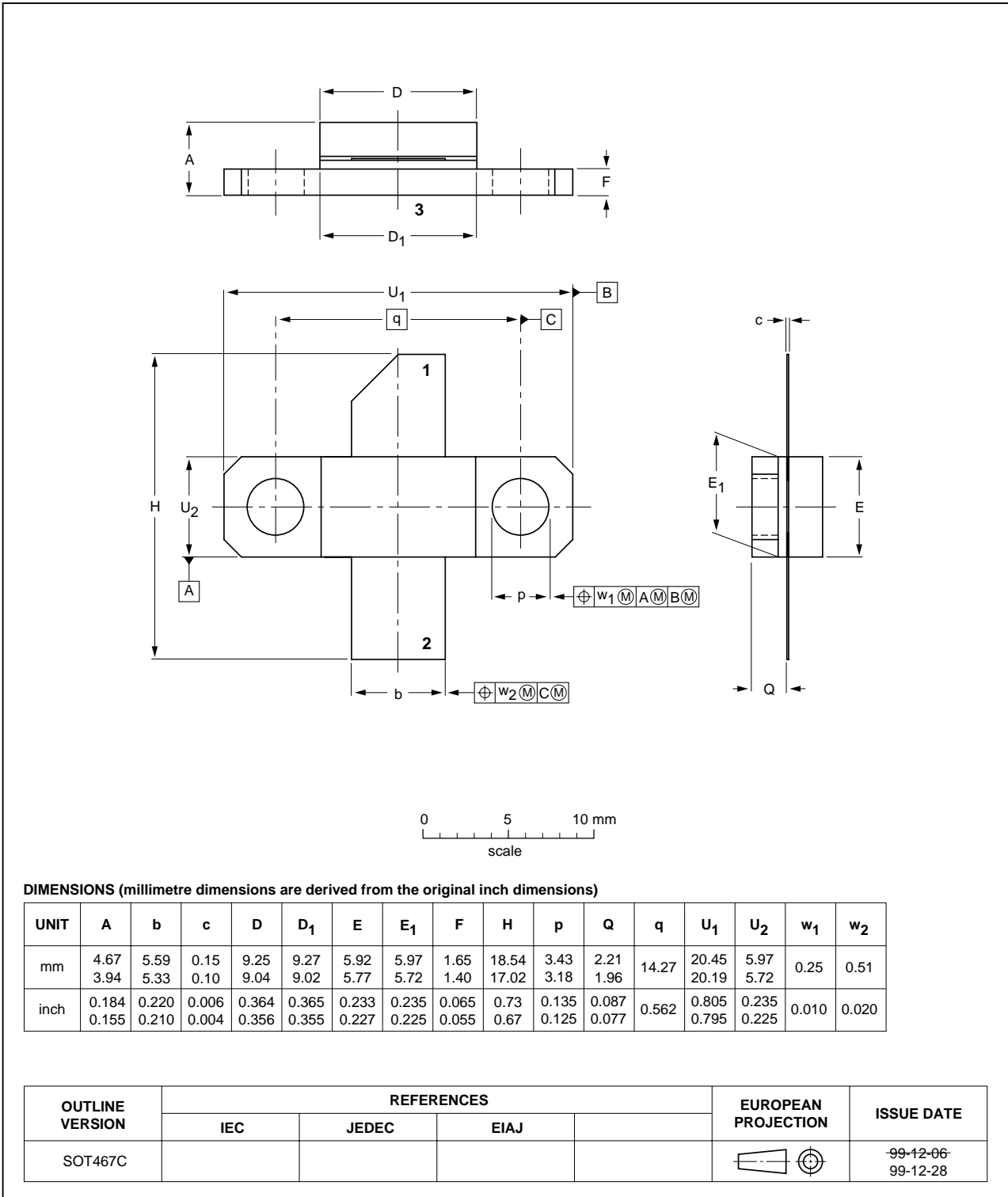


Fig 11. Package outline SOT467C

## 10. Abbreviations

**Table 10. Abbreviations**

Acronym	Description
CDMA	Code Division Multiple Access
EDGE	Enhanced Data rates for the GSM Evolution
GSM	Global System for Mobile communications
HF	High Frequency
LDMOS	Laterally Diffused Metal Oxide Semiconductor
LDMOST	Laterally Diffused Metal-Oxide Semiconductor Transistor
PHS	Personal HandyPhone System
RF	Radio Frequency
SMD	Surface-Mount Device
UHF	Ultra High Frequency
VSWR	Voltage Standing-Wave Ratio
W-CDMA	Wideband Code Division Multiple Access

## 11. Revision history

**Table 11. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
BLF3G21-30_1	20070214	Product data sheet	-	-

## 12. Legal information

### 12.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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**14. Contents**

**1 Product profile . . . . . 1**

1.1 General description . . . . . 1

1.2 Features . . . . . 1

1.3 Applications . . . . . 2

**2 Pinning information . . . . . 2**

**3 Ordering information . . . . . 2**

**4 Limiting values . . . . . 2**

**5 Thermal characteristics . . . . . 3**

**6 Characteristics . . . . . 3**

**7 Application information . . . . . 3**

7.1 Ruggedness in class-AB operation . . . . . 4

**8 Test information . . . . . 6**

**9 Package outline . . . . . 9**

**10 Abbreviations . . . . . 10**

**11 Revision history . . . . . 10**

**12 Legal information . . . . . 11**

12.1 Data sheet status . . . . . 11

12.2 Definitions . . . . . 11

12.3 Disclaimers . . . . . 11

12.4 Trademarks . . . . . 11

**13 Contact information . . . . . 11**

**14 Contents . . . . . 12**

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